

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM705412

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
3D GLASS SOLUTIONS, INC.		01/27/2022	Corporation: NEVADA
RECEIVING PARTY DATA			
Name:	SILICON VALLEY BANK		
Street Address:	3003 Tasman Drive		
City:	Santa Clara		
State/Country:	CALIFORNIA		
Postal Code:	95054		
Entity Type:	Corporation: CALIFORNIA		
PROPERTY NUMBERS Total: 2			
Property Type	Number	Word Mark	
Registration Number:	4958658	3D 3D GLASS SOLUTIONS	
Registration Number:	3644084	APEX	
CORRESPONDENCE DATA			
Fax Number:	2125046666		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	2125046000		
Email:	jennifer.chick@cwt.com		
Correspondent Name:	Cadwalader, Wickersham & Taft LLP		
Address Line 1:	200 Liberty Street		
Address Line 4:	New York, NEW YORK 10281		
ATTORNEY DOCKET NUMBER:	90717.230		
NAME OF SUBMITTER:	Jennifer A. Chick		
SIGNATURE:	/Jennifer A. Chick/		
DATE SIGNED:	01/28/2022		
Total Attachments: 9			
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement (“**Agreement**”) is entered into as of January 27, 2022 by and between SILICON VALLEY BANK, a California corporation (“**Bank**”), and 3D GLASS SOLUTIONS, INC., a Nevada corporation (“**Grantor**”).

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodation to Grantor (the “**Loans**”) in the amounts and manner set forth in that certain Loan and Security Agreement by and between Bank and Grantor dated as of the Effective Date (as the same may be amended, modified or supplemented from time to time, the “**Loan Agreement**”; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Grantor, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks, Patents, and Mask Works (as each term is described below) to secure the obligations of Grantor under the Loan Agreement.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor’s right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Loan Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

1. Grant of Security Interest. To secure its obligations under the Loan Agreement, Grantor grants and pledges to Bank a security interest in all of Grantor’s right, title and interest in, to and under its intellectual property (all of which shall collectively be called the “Intellectual Property Collateral”), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work or authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the “**Copyrights**”);

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto and any patents and patent applications claiming the priority benefit of the patents and patent applications set forth on Exhibit B attached hereto (collectively, the “**Patents**”);

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the “**Trademarks**”);

(f) All mask works or similar rights available for the protection of semiconductor chips, now owned or hereafter acquired, including, without limitation those set forth on Exhibit D attached hereto (collectively, the “**Mask Works**”);

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, Trademarks, or Mask Works and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, Patents, or Mask Works; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. Recordation. Grantor authorizes the Commissioner for Patents, the Commissioner for Trademarks and the Register of Copyrights and any other government officials to record and register this Agreement upon request by Bank.

3. Authorization. Grantor hereby authorizes Bank to (a) modify this Agreement unilaterally by amending the exhibits to this Agreement to include any Intellectual Property Collateral which Grantor obtains subsequent to the date of this Agreement, and (b) file a duplicate original of this Agreement containing amended exhibits reflecting such new Intellectual Property Collateral.

4. Loan Documents. This Agreement has been entered into pursuant to and in conjunction with the Loan Agreement, which is hereby incorporated by reference. The provisions of the Loan Agreement shall supersede and control over any conflicting or inconsistent provision herein. The rights and remedies of Bank with respect to the Intellectual Property Collateral are as provided by the Loan Agreement and related documents, and nothing in this Agreement shall be deemed to limit such rights and remedies.

5. Execution in Counterparts. This Agreement may be executed in counterparts (and by different parties hereto in different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page to this Agreement by facsimile or in electronic (i.e., “pdf” or “tif” format) shall be effective as delivery of a manually executed counterpart of this Agreement.

6. Successors and Assigns. This Agreement will be binding on and shall inure to the benefit of the parties hereto and their respective successors and assigns.

7. Governing Law. This Agreement and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Agreement and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the laws of the United States and the State of California, without giving effect to any choice or conflict of law provision or rule (whether of the State of California or any other jurisdiction).

[Signature page follows.]

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

3D GLASS SOLUTIONS, INC.

DocuSigned by:
By: Adam Gushard
Name: Adam Gushard
Title: Chief Financial Officer

BANK:

SILICON VALLEY BANK

DocuSigned by:
By: William Sealy
Name: William Sealy
Title: Vice President

EXHIBIT A

Copyrights

None identified

EXHIBIT B

Patents

No.	Country	Patent No./ Appl. No.	Issue Date / Filing Date	Title	Owner
1.	U.S.	11,161,773	11/02/2021	METHODS OF FABRICATING PHOTSENSITIVE SUBSTRATES SUITABLE FOR OPTICAL COUPLER	3D Glass Solutions, Inc.
2.	U.S.	11,139,582	10/5/2021	HIGH EFFICIENCY COMPACT SLOTTED ANTENNA WITH A GROUND PLANE	3D Glass Solutions, Inc.
3.	U.S.	11,101,532	8/24/2021	RF CIRCULATOR	3D Glass Solutions, Inc.
4.	U.S.	11,076,489	7/27/2021	RF INTEGRATED POWER CONDITION CAPACITOR	3D Glass Solutions, Inc.
5.	U.S.	10,903,545	1/6/2021	METHOD OF MAKING A MECHANICALLY STABILIZED RADIO FREQUENCY TRANSMISSION LINE DEVICE	3D Glass Solutions, Inc.
6.	U.S.	10,854,946	12/1/2020	COUPLED TRANSMISSION LINE RESONATE RF FILTER	3D Glass Solutions, Inc.
7.	U.S.	10,665,377	5/26/2020	2D and 3D inductors antenna and transformers fabricating photoactive substrates	3D Glass Solutions, Inc.
8.	U.S.	10,201,091	2/5/2019	Photo-Definable Glass with Integrated Electronics and Ground Plane	3D Glass Solutions, Inc.
9.	U.S.	10,070,533	9/4/2018	PHOTO-DEFINABLE GLASS WITH INTEGRATED ELECTRONICS AND GROUND PLANE	3D Glass Solutions, Inc.
10.	U.S.	8,709,702	4/9/2014	METHODS TO FABRICATE A PHOTOACTIVE SUBSTRATE SUITABLE	3D Glass Solutions, Inc.

No.	Country	Patent No./ Appl. No.	Issue Date / Filing Date	Title	Owner
				FOR MICROFABRICATION	
11.	U.S.	17/348,378	6/15/2021	Radio frequency (RF) integrated power-conditioning capacitor	3D Glass Solutions, Inc.
12.	U.S.	17/259,887	1/12/2021	Annular Capacitor RF, Microwave and MM Wave Systems	3D Glass Solutions, Inc.
13.	U.S.	17/263,805	1/27/2021	Heterogenous Integration for RF, Microwave and MM Wave Systems in Photoactive Glass Substrates	3D Glass Solutions, Inc.
14.	U.S.	17/030,089	9/23/2020	Coupled Transmission Line Resonate RF Filter	3D Glass Solutions, Inc.
15.	U.S.	16/767,096	5/26/2020	Impedence Matching Conductive Structure for High Efficiency RF Circuits	3D Glass Solutions, Inc.
16.	U.S.	16/850,571	4/16/2020	2D and 3D Inductors Antenna and Transformers Fabricating Photoactive Substrates	3D Glass Solutions, Inc.
17.	U.S.	16/622,421	12/13/2019	2D & 3D RF Lumped Element Devices for RF System in a Package Photoactive Glass Substrates	3D Glass Solutions, Inc.
18.	U.S.	16/072,828	7/25/2018	Multi-Layer Photo Definable Glass with Integrated Devices	3D Glass Solutions, Inc.
19.	U.S.	16/079,033	8/22/2018	3D Capacitor and Capacitor Array Fabricating Photoactive Substrates	3D Glass Solutions, Inc.

EXHIBIT C

Trademarks


No.	Country	Trademark	Registration Number / Serial Number	Registration Date / Filing Date	Owner
1.	U.S.	 3D GLASS SOLUTIONS	4,958,658	5/17/2016	3D Glass Solutions, Inc.
2.	U.S.	APEX	3,644,084	6/23/2009	3D Glass Solutions, Inc.

EXHIBIT D

Mask Works

None identified